L Number	Hits	Search Text	DB	Time stamp
1	27408	tape with carrier	USPAT; US-PGPUB; EPO; JPO;	2004/09/29 09:34
2	68781	tcp (tape with carrier with (package packaged packaging)) (tape with carrier)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/29 09:36
3	2598502	semiconductor die dice chip ic (integrated adj circuit)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/29 09:37
4	1426855	leadframe lead (lead adj frame)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/29 09:37
5	9959	(tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/29 09:38
6	3301	lead (lead adj frame)) (tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/29
7	415339	<pre>(integrated adj circuit)) same (leadframe lead (lead adj frame)) (leadframe lead (lead adj frame)) and (trace land pad electrode)</pre>	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/29 09:39
8	609711	(leadframe lead (lead adj frame)) and (trace land pad terminal electrode)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/29 09:39
9	2291	packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40
10	6781	<pre>pad terminal electrode) ((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40
11	1184	(((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)) and (bga ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40